

AMENDMENTS

In the Specification:

Page 5, please replace paragraph [0028] with the following:

[0028] Next, a ball grid array 130 in the form of solder bumps, is formed on the lower surface of the substrate 122 by conventional positioning (Figure 3F). To attach the solder bumps of the ball grid array 130, a flux is added to the solder prior to placement and, after placement, the solder is reflowed using known reflow techniques. The solder bumps of the ball grid array 130 are thereby connected to the conductive traces of the substrate 122 and through the wire bonds 126 to the semiconductor die 124. The ball grid array 130 [[134]] provides signal and power connections as well as ground connections for the semiconductor die 124.

Page 6, please replace paragraph [0038] with the following:

[0038] Next, a ball grid array 130 in the form of solder bumps, is formed on the exposed portions of the solder balls 134 by conventional positioning (Figure 7F). To attach the solder bumps of the ball grid array 130, a flux is added to the solder prior to placement and, after placement, the solder is reflowed using known reflow techniques. The solder bumps of the ball grid array 130 are thereby connected to the conductive traces of the substrate 122 and through the wire bonds 126 to the semiconductor die 124. The ball grid array 130 [[134]] provides signal and power connections as well as ground connections for the semiconductor die 124.

Page 8, please replace paragraph [0048] with the following:

[0048] Reference is now made to Figures 9A to 9I to describe a process for manufacturing a ball grid array package 120 in accordance with yet another embodiment of the present invention. Referring to Figure 9A [[8A]], the substrate 122 of a polyimide tape is shown. The substrate 122 includes a metal layer on the bottom side thereof which includes a circuit pattern of conductive

traces for signal transfer. A cavity extends through the substrate 122 and a plurality of smaller holes also extend through the substrate. It will be understood that the substrate 122 is in the form of an array strip for producing a number of BGA units. Two such units are depicted in an array in Figure 9A [[8A]], however, the process is herein described with reference to a single unit.